

Curriculum Vitae
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Xuejun Fan
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Xuejun Fan is a Regents' Professor of Texas State University System, a University Professor, a Mary Ann and Lawrence E. Faust Endowed Professor

He received University Scholar Award in 2017. He is Larry Lawson Research Fellow (2017-2020), Distinguished Faculty Research Fellow (2015-2018, 2018-2021), and Presidential Faculty Fellow (2014-2016). He was also selected as Inaugural Faculty Mentor Award in 2015.

Dr. Fan received the Outstanding Sustained Technical Contribution Award in 2017, and Exceptional Technical Achievement Award in 2011, from the IEEE Electronic Packaging Society.

In his early academia career in China, Dr. Fan was the recipient of a Young Faculty Award from the Fok Ying-Tung Education Foundation, Hong Kong in 1994. He received the nominee for the title of "Ten Outstanding Youth of China" in 1991.

Education

12/1989	Ph.D. in Solid Mechanics	Tsinghua University, Beijing, China
11/1986	M.S. in Applied Mechanics	Tianjin University, Tianjin, China
07/1984	B.S. in Applied Mechanics	Tianjin University, Tianjin, China

Appointments

09/2019-present	Visiting/Guest Professor, Delft University of Technology, Delft, the Netherlands
09/2013-present	Professor, Lamar University, Beaumont, Texas
08/2007-08/2013	Associate Professor, Lamar University, Beaumont, Texas
01/2004-08/2007	Senior Staff Engineer, Intel Corporation, Chandler, Arizona
09/2000-12/2003	Senior Member Research Staff, Philips Research, Briarcliff Manor, New York
09/1997-10/2000	Member Technical Staff, Institute of Microelectronics, Singapore
05/1996-09/1997	Visiting Professor, University of British Columbia, Vancouver, Canada
11/1991-09/1997	Professor, Taiyuan University of Technology, Taiyuan, China
04/1994-09/1997	Director, Institute of Applied Mechanics, Taiyuan University of Technology, Taiyuan, China
03/1993-03/1994	Research Fellow, University of Tokyo, Tokyo, Japan
08/1990-04/1994	Associate Chair, Department of Mathematics, Physics and Mechanics, Taiyuan University of Technology, Taiyuan, China
12/1989-11/1991	Assistant Professor, Taiyuan University of Technology, Taiyuan, China

Honors and Awards

1. Regents' Professor Award, Texas State University System, 2019.
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10. Nominee, Minnie Stevens Piper Professor Award, Minnie Stevens Piper Professor Award Foundation, 2016.
11. Faculty Mentor Award, Lamar University, 2015.
12. Presidential Faculty Fellow, Lamar University, 2015-2016.
13. Distinguished Faculty Research Fellow, Lamar University, 2015-2018.
14. Presidential Faculty Fellow, Lamar University, 2014-2015.
15. Global SSL Events of the Year 2012-2013, International Solid State Lighting Association (ISA), 2013.
16. Full Professorship, early promotion, Lamar University, 2013.
17. Exceptional Technical Achievement Award, IEEE Electronic Packaging Society. 2011.
18. Nominee of Advisor of the Year, the Center for Academic Success (CAS), Lamar University, 2011.
19. Significant Contribution Award, International Conference on Electronic Packaging Technology (ICEPT), 2009.
20. Outstanding Contribution Award, International Conference on Thermal and Thermal-Mechanical Simulation and Experiment in Microelectronics and Microsystems (EuroSimE). 2009.
21. Best Paper Award, IEEE Transactions on Components and Packaging Technologies. 2009.
22. IEEE Distinguished Lecturer, IEEE Electronic Packaging Society, 2008.
23. Technical Achievement Award, Intel Corporation. 2006.
24. Outstanding Team Contribution Award, Intel Corporation. 2006.
25. Best Presentation Award, Annual Quality and Reliability Symposium, Intel Corporation. 2006.
26. Technical Achievement Award, Intel Corporation. 2005.
27. Outstanding Team Contribution, Intel Corporation. 2005.
28. Excellence Award, Intel Corporation. 2005.
29. Star Award, P11.04 00000912 0 612 792 reW*ñq0.00000912 0 612 792 reW*ñs0 g(p)4(rom)nb0912 0 6sETC

21. Electronics Packaging Community Readiness for Heterogeneous Integration Challenges in 2020 and beyond, Panel Forum, International Conference on Thermal, Mechanical and Multi-Physics Simulation and Experiments in Microelectronics and Microsystems (EuroSimE), Dresden, Germany. 2-5 April 2017. (Invited Talk).
22. In-Situ Characterization of Moisture Absorption and Hygroscopic Swelling of Silicone/Phosphor Composite Film and Epoxy Mold Compound in LED Packaging. 2017 18th International Conference on Thermal, Mechanical and Multi-Physics Simulation and Experiments in Microelectronics and Microsystems (EuroSimE), Dresden, Germany. 2-5 April 2017. (Session keynote).
23. LED Packaging, System and, and Reliability Considerations. Professional C0.00000912 0 612 792 reW*ñBT/F2

37.

55. Reliability study in micro-/nano- electronics systems. Guilin University of Electronics Technology, Guilin, June 28, 2011 (invited talk).
56. Reliability issues in microelectronics packaging. Guilin University of Electronics Technology, Guilin, June 29, 2011 (invited talk).
57. Multiphysics modeling of microelectronics packaging and microsystems. Guilin University of Electronics Technology, Guilin, June 29, 2011 (invited talk).
58. Wafer level integration of solid state lighting system. International Seminar of Solid State Lighting Packaging and Integration. Guilin University of Electronics Technology, Beijing, China. August 16, 2011 (keynote).
59. Multiphysics modeling of microelectronics packaging and microsystems. International Conference on Thermal, Mechanical and Multiphysics Simulation and Experiments in Micro-Electronics and Micro-Systems (EuroSimE 2011). , Linz, Austria, April 17, 2011 (short course).
60. Moisture diffusion and integrated stress analysis in encapsulated microelectronics devices. International Conference on Thermal, Mechanical and Multiphysics Simulation and Experiments in Micro-Electronics and Micro-Systems (EuroSimE 2011). Linz, Austria, April 19, 2011 (session keynote).
61. Moisture related reliability in electronic packaging. 61st Electronic Components and Technology Conference (61st ECTC), Orlando, Florida. May 31, 2011 (professional development course).
62. Reliability study in micro-/nano- electronics systems. China Petroleum University, Qingdao, Shandong, China, May 17, 2011 (invited talk).
63. Reliability study in micro-/nano- electronics systems. Shandong University, Weihai, China, May 17, 2011 (invited talk).
64. Wafer level packaging (WLP): fan-in, fan-out and three-dimensional integration. 11th. Int. Conf. on Thermal, Mechanical and Multiphysics Simulation and Experiments in Micro-Electronics and Micro-Systems (EuroSimE 2010). Bordeaux, France, April 25-18, 2010 (plenary keynote).
65. Advances in moisture related reliability in electronic packaging, National Semiconductor Corp., Santa Clara, CA, July 11, 2010 (invited tutorial).
66. Wafer level packaging, past, present and future. Huatian Advanced Packaging Forum, Tianshui, Gansu, China August 14, 2010 (keynote presentation).
67. Moisture related reliability in electronic packaging. Electronic Components and Technology Conference (60th

95. Advances in reliability mechanics in microelectronics and microsystems. International Conference on Electronic Packaging Technology (ICEPT), August 2006 (invited short course).
96. Moisture related reliability in electronic packaging. Electronic Component Technology

Steering Committee, EPS Representative, Electronic Components and Technology Conference (ECTC), 2018 – 2021.

Panel Member, Electronics Packaging Community Readiness for Heterogeneous Integration Challenges in 2020 and beyond, International Conference on Thermal, Mechanical and Multi-Physics Simulation and Experiments in Microelectronics and Microsystems (EuroSimE), Dresden, Germany. 2-5 April 2017.

Chair, Heterogeneous Integration Roadmap (HIR) Forum, International Conference on Electronic Packaging Technology, Wuhan, China, 2016.

Conference Co-Chair, International Conference on Electronic Packaging Technology (ICEPT). 2015.

Committee Chair, Thermal Mechanical Modeling and Characterization, Electronic Packaging and Technology Conference (EPTC). 2015.

Advisory Committee Member, International Electronics Manufacturing Technology (IEMT), 2014.

Conference Session Chair, International Conference on Fracture (ICF13). 2013.

Program Committee Member, Electronic System Technologies Conference (ESTC). 2013.

Technical Committee Member, International Reliability Pety Perno Conference (ESTC). 2013.

Technical Committee Member, European Conference on Reliability of Electron Devices (ESREF). 2009~present.

Program Committee Member, International Congress on Reliability in Microelectronics and Nanoelectronics. 2006.

Program Committee Member, Modeling and Simulation, IEEE Electronic Components and Technology Conference (ECTC). 2005 ~ present.

Session Chairs, IEEE Electronic Components and Technology Conference (ECTC). 2005 ~ present.